

Bill of Materials

TI DESIGNS

TIDA-00301

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint
1	7	C1, C2, C4, C5, C8, C9, C10	0.1uF	CAP, CERM, 0.1uF, 10V, +/-10%, X5R, 0201	Samsung	CL03A104KP3NNNC	0201
2	1	C3	470nF	CAP, CERAMIC, 470nF, 10%, 16V, X5R, 0402	TDK	C1005X5R1C474K	
3	1	C6	2.2uF	CAP, TANTALUM, 2.2uF, 20%, 10V, 0603	ROHM SEMICONDUCTOR	TCM1A225M8R	
4	1	C7	33uF	CAP, TANTALUM, 33uF, 20%, 6.3V, 1.5 OHM, 0603	Vishay Sprague	TR8M336M6R3C1500	
5	1	C11	2200pF	CAP, CERM, 2200pF, 10V, +/-10%, X5R, 0201	MuRata	GRM033R61A222KA01D	0201
6	1	C12	10uF	CAP, TANTALUM, 10UF, 20%, 6.3V, 6 OHM, SMT0603	NICHICON	F980J106MMA	
7	1	D1	GREEN	LED, GREEN, SMT0402	KINGBRIGHT	APHHS1005CGCK	
8	1	J1		22pin SPO2 Module Connector pads		NA	PCB only
9	1	R1	1.0Meg	RES, 1.0Meg ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04021M00JNED	0402
10	1	R2	0	RES, 0 ohm, 5%, 0.05W, 0201	Panasonic	ERJ-1GE0R00C	0201
11	1	R3	3.3k	RES, 3.3k ohm, 1%, 0.05W, 0201	Samsung Electro-Mechanics America, Inc	RC0603F332CS	0201
12	1	R4	47k	RES, 47k ohm, 1%, 0.05W, 0201	Samsung Electro-Mechanics America, Inc	RC0603F473CS	0201
13	1	U1		BGA, 36 PINS	TEXAS INSTRUMENTS	AFE4403YZPR	YZP
14	1	U2	MSP430F5528IYFF	IC, MIXED SIGNAL MICROCONTROLLER, BGA-64	TEXAS INSTRUMENTS	MSP430F5528IYFFR	
15	1	U3	-	Multichip LED and photodiode package with a Green LED, Red LED, IR LED and a photodetector	OSRAM	SFH7050	Multichip LED and photodiode package with a Green LED, Red LED, IR LED and a photodetector
16	1	Y1	16MHz	CRYSTAL, PIEZO CERAMIC RESONATOR, 16.00 MHz, SMD, 0.5%, 15pF, SMD	MURATA	CSTCE16M0V53-R0	

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